

## ABSTRACT

An insulating material comprising a cycloolefin polymer, specifically, an interlayer insulating material for a high-density assembly board having interlayer-connecting via holes at most 200  $\mu\text{m}$  in diameter, comprising a cycloolefin polymer containing at least 50 mol% of a repeating unit derived from a cycloolefin monomer; a dry film formed from a curable resin composition comprising a polymer having a number average molecular weight within a range of 1,000 to 1,000,000 as measured by gel permeation chromatography, and a hardener; and a resin-attached metal foil obtained by forming a film of a cycloolefin polymer on one side of a metal foil.

15 Laminates, multi-layer laminates and build-up multi-layer laminates making use of these materials, and production processes thereof.